

NOTE1. LEAD CO-PLANARITY SHALL BE 0.1mmMAX  
 2. AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.  
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MONUTED TO FPC.

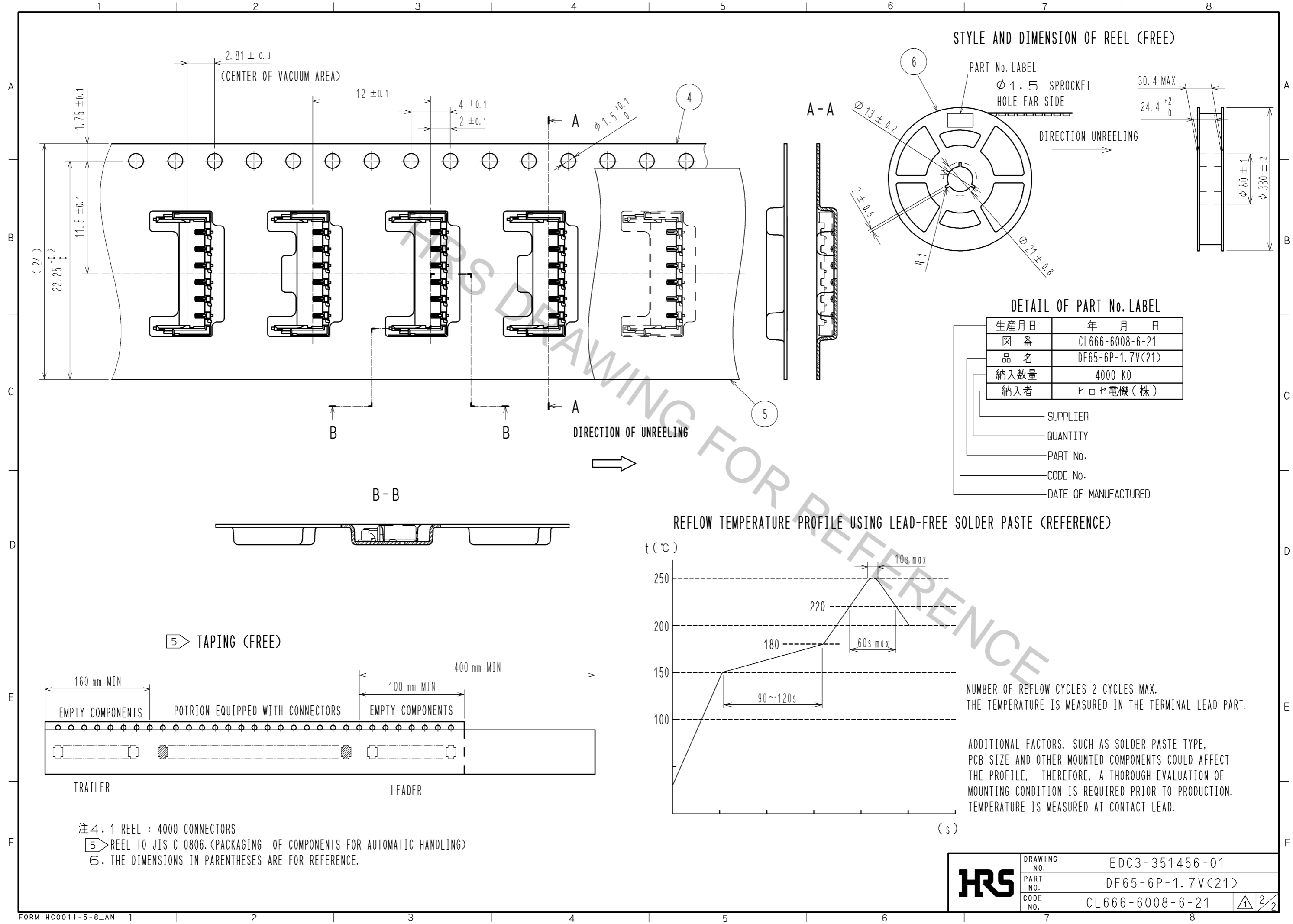
NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	BRASS	SURFACE:TIN PLATING 1μmMIN UNDER PLATING:NICKEL PLATING 0.5μmMIN		6	PS		REEL. BLACK
2	BRASS	SURFACE:TIN PLATING 1μmMIN UNDER PLATING:NICKEL PLATING 0.5μmMIN		5	POLYESTER		CLEER(COVER TAPE)
1	LCP	UL94V-0. BLACK		4	PS		CLEER(CENBOSSED CARRIER TAPE)

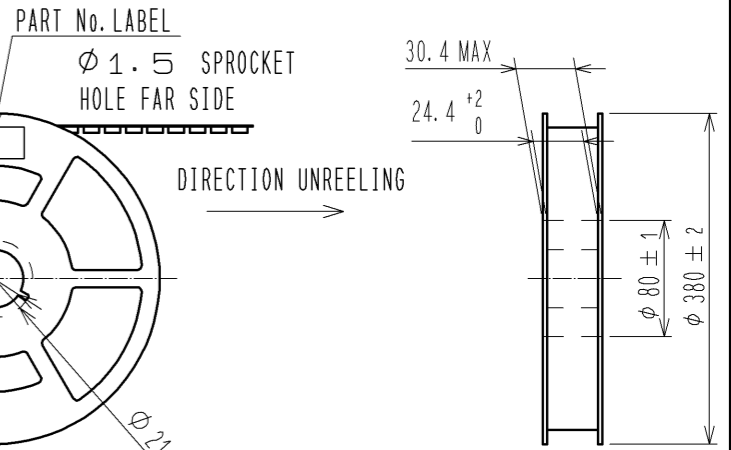
UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	10:1	3	DIS-H-008243	TT. OHSAKO	OM. MIYAMOTO	13.10.22

APPROVED	DATE	DRAWING NO.
KI. AKIYAMA	13.08.22	EDC3-351456-01
CHECED	DATE	PART NO.
OM. MIYAMOTO	13.08.21	DF65-6P-1.7V(21)
DESIGNED	DATE	CODE NO.
TT. OHSAKO	13.08.21	CL666-6008-6-21
DRAWN	DATE	
TT. OHSAKO	13.08.21	



STYLE AND DIMENSION OF REEL (FREE)

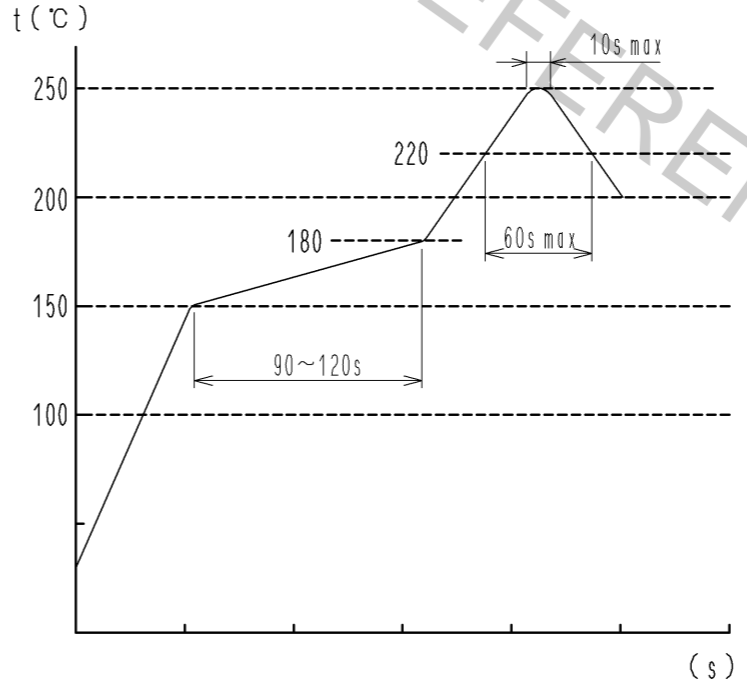


DETAIL OF PART No. LABEL

生産月日	年 月 日
箱 番	CL666-6008-6-21
品 名	DF65-6P-1.7V(21)
納入数量	4000 KO
納入者	ヒロセ電機(株)

- SUPPLIER
- QUANTITY
- PART No.
- CODE No.
- DATE OF MANUFACTURED

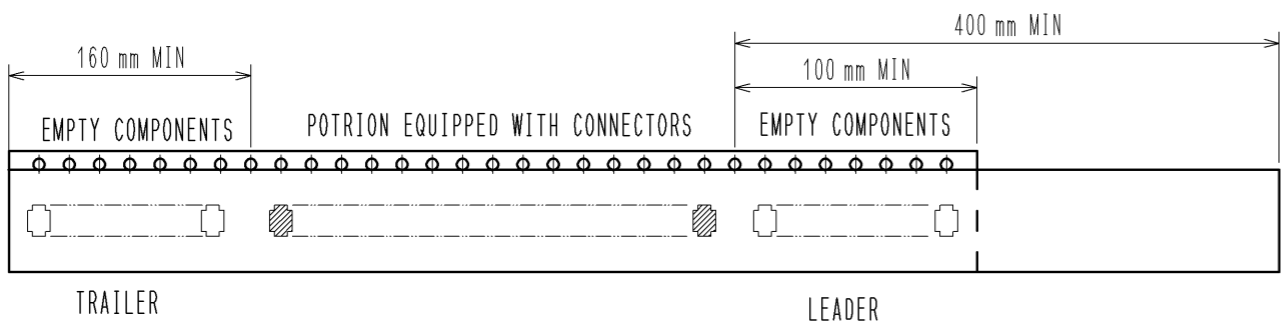
REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES 2 CYCLES MAX.  
THE TEMPERATURE IS MEASURED IN THE TERMINAL LEAD PART.

ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE,  
PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT  
THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF  
MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION.  
TEMPERATURE IS MEASURED AT CONTACT LEAD.

5 TAPING (FREE)



注4.1 REEL : 4000 CONNECTORS  
5 REEL TO JIS C 0806.(PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)  
6. THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.

<b>HRS</b>	DRAWING NO.	EDC3-351456-01
	PART NO.	DF65-6P-1.7V(21)
	CODE NO.	CL666-6008-6-21
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